

## STANDARD CAPACITANCE TVS ARRAY

### APPLICATIONS

- ✓ Notebook Computers
- ✓ Cellular Phone Base Stations
- ✓ Personal Digital Assistant (PDA)
- ✓ Digital Cameras

### IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- ✓ 61000-4-4 (EFT): 40A - 5/50ns

### FEATURES

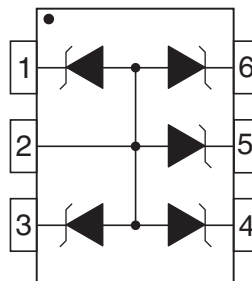
- ✓ 100 Watts Peak Pulse Power per Line (tp=8/20µs)
- ✓ Monolithic Design
- ✓ Available in Multiple Voltage Types Ranging From 5V to 24V
- ✓ Protect 4 Lines Bidirectional and 5 Lines Unidirectional
- ✓ ESD Protection > 25 kilovolts
- ✓ Low Clamping Voltage

### MECHANICAL CHARACTERISTICS

- ✓ Molded JEDEC SC-70-6L Package
- ✓ Weight 14 milligrams (Approximate)
- ✓ Flammability rating UL 94V-0
- ✓ 8mm Tape and Reel Per EIA Standard 481
- ✓ Marking: Marking Code & Pin One Defined By DOT on Package



### PIN CONFIGURATIONS

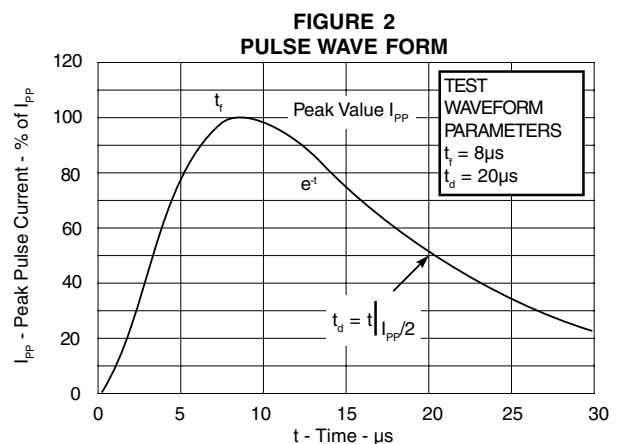
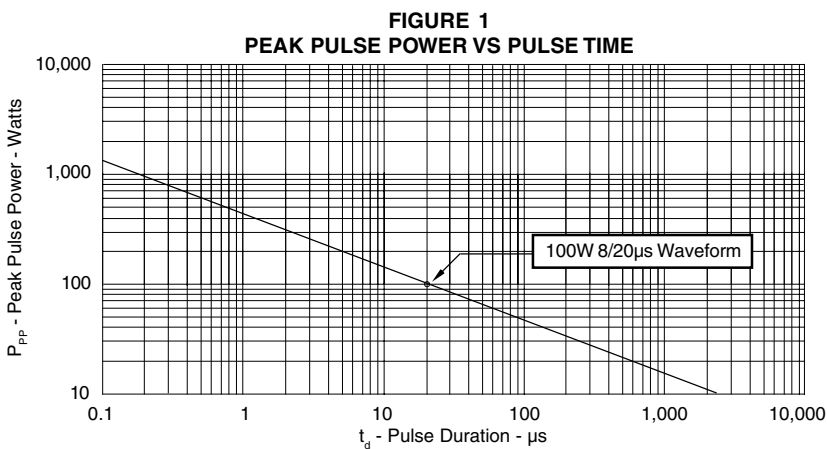


**DEVICE CHARACTERISTICS**

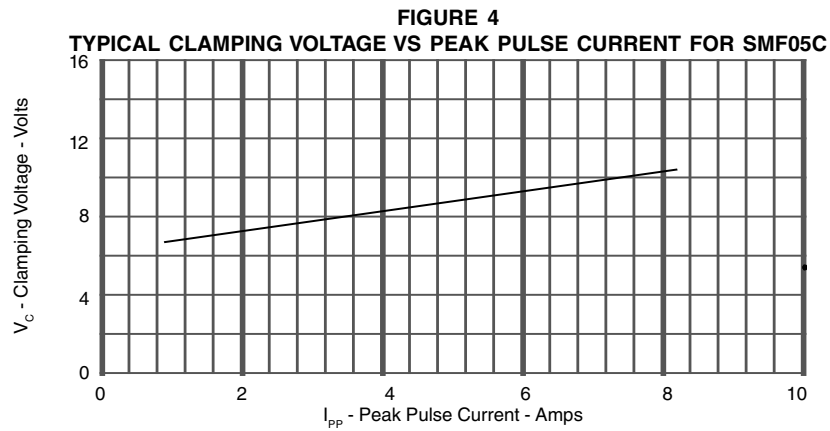
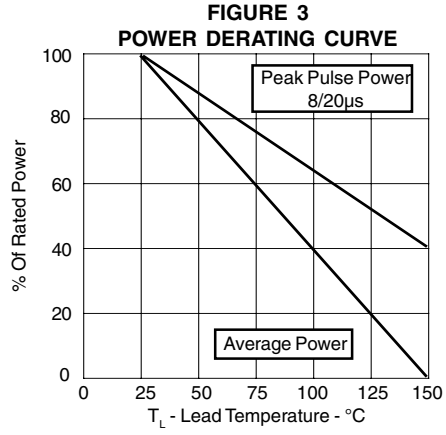
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ( $t_p = 8/20\mu s$ ) - See Figure 1	$P_{PP}$	100	Watts
Operating Temperature	$T_J$	-55°C to 150°C	°C
Storage Temperature	$T_{STG}$	-55°C to 150°C	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified							
PART NUMBER	DEVICE MARKING	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT	TYPICAL CAPACITANCE (See Note 1)
		$V_{WM}$ VOLTS	@ 1mA $V_{(BR)}$ VOLTS	@ $I_p = 5A$ $V_C$ VOLTS	@ 8/20 $\mu s$ $V_C @ I_{PP}$	@ $V_{WM}$ $I_D$ $\mu A$	@ 0V, 1 MHz $C_J$ pF
SMF05C	05C	5.0	6.0	9.8	10.0V @ 10.0A	5	60
SMF12C	12C	12.0	13.3	-	23.8V @ 4.2A	1	30
SMF15C	15C	15.0	16.7	-	33.3V @ 3.0A	1	25
SMF24C	24C	24.0	26.7	-	55.5V @ 1.8A	1	20

**Note 1:** Pins 1, 3, 4, 5 or 6 to pin 2.



GRAPHS



## APPLICATION NOTE

The SMFC Series are TVS arrays designed to protect I/O or data lines from the damaging effects of ESD or EFT. This product provides both unidirectional and bidirectional protection, with a surge capability of 100 Watts  $P_{pp}$  per line for an 8/20 $\mu$ s waveshape and ESD protection > 25 kilovolts.

### UNIDIRECTIONAL COMMON-MODE CONFIGURATION (Figure 1)

The SMFC Series provides up to four (4) lines of protection in a common-mode configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- ✓ Line 1 is connected to Pin 1.
- ✓ Line 2 is connected to Pin 3.
- ✓ Line 3 is connected to Pin 4.
- ✓ Line 4 is connected to Pin 6.
- ✓ Pin 2 is connected to ground.

### BIDIRECTIONAL DIFFERENTIAL-MODE CONFIGURATION (Figure 2)

The SMFC Series provides up to five (5) lines of protection in a differential-mode configuration as depicted in Figure 2.

Circuit connectivity is as follows:

- ✓ Line 1 is connected to Pin 1.
- ✓ Line 2 is connected to Pin 3.
- ✓ Line 3 is connected to Pin 4.
- ✓ Line 4 is connected to Pin 5.
- ✓ Line 5 is connected to Pin 6.
- ✓ Pin 2 is not connected.

Figure 1 - Unidirectional Configuration  
Common-Mode I/O Port Protection

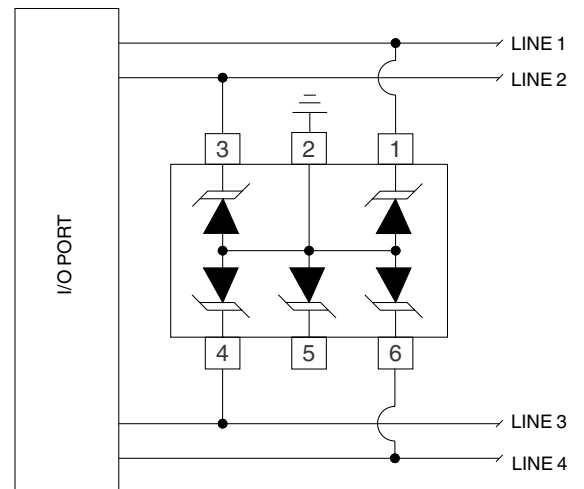
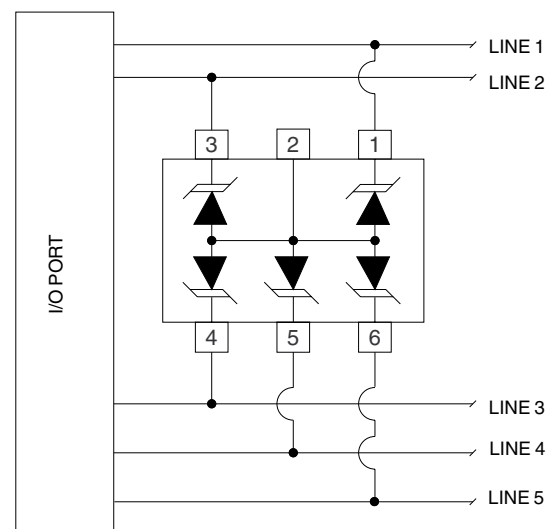


Figure 2 - Bidirectional Configuration  
Differential-Mode I/O Port Protection



### CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- ✓ The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- ✓ The path length between the TVS device and the protected line should be minimized.
- ✓ All conductive loops including power and ground loops should be minimized.
- ✓ The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- ✓ Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

**PACKAGE OUTLINE & DIMENSIONS**

### PACKAGE OUTLINE

**SC70-6L**

### PACKAGE DIMENSIONS

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.90	2.15	0.074	0.084
B	1.15	1.35	0.045	0.055
C	0.80	1.00	0.031	0.040
D	0.15	0.30	0.006	0.012
E	0.65 BSC	-	0.0255 BSC	-
F	1.30 BSC	-	0.0512 BSC	-
G	0.80	1.10	0.031	0.043
J	0.08	0.25	0.003	0.010
K	2.00	2.20	0.078	0.086
L	0	0.10	0	0.004
M	0.26	0.46	0.010	0.018

### MOUNTING PAD

TYPICAL		
DIM	Millimeters	Inches
1	0.50	0.020
2	1.30	0.051
3	0.65	0.026
4	2.40	0.094
5	0.60	0.024
6	0.70	0.028
7	2.50	0.098

### NOTES

1. Dimensioning and tolerances per ANSI Y14.5M, 1985.
2. Controlling Dimension: Inches
3. Dimensions are exclusive of mold flash and metal burrs.

### TAPE & REEL ORDERING NOMENCLATURE

1. Surface mount product is taped and reeled in accordance with EIA-481.
2. Suffix-T7 = 7 Inch Reel - 3,000 pieces per 8mm tape, i.e., *SMF05C-T7*.

**Outline & Dimensions: Rev 1 - 11/01, 06019**

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